



**Advanced Power  
Electronics Corp.**

**AP40N03GP**

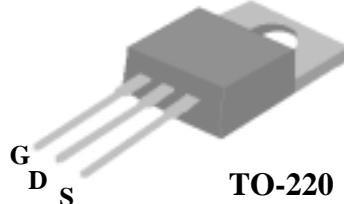
**Pb Free Plating Product**

**N-CHANNEL ENHANCEMENT MODE  
POWER MOSFET**

▼ Low Gate Charge

▼ Simple Drive Requirement

▼ Fast Switching

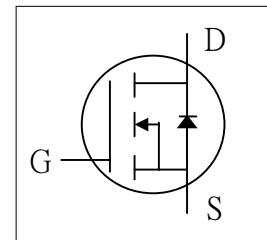


$BV_{DSS}$	30V
$R_{DS(ON)}$	17mΩ
$I_D$	40A

## Description

The Advanced Power MOSFETs from APEC provide the designer with the best combination of fast switching, ruggedized device design, low on-resistance and cost-effectiveness.

The TO-220 package is universally preferred for all commercial-industrial applications and suited for low voltage applications such as DC/DC converters and high efficiency switching circuits.



## Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	30	V
$V_{GS}$	Gate-Source Voltage	$\pm 20$	V
$I_D @ T_C = 25^\circ C$	Continuous Drain Current, $V_{GS} @ 10V$	40	A
$I_D @ T_C = 100^\circ C$	Continuous Drain Current, $V_{GS} @ 10V$	30	A
$I_{DM}$	Pulsed Drain Current <sup>1</sup>	169	A
$P_D @ T_C = 25^\circ C$	Total Power Dissipation	50	W
	Linear Derating Factor	0.4	W/°C
$T_{STG}$	Storage Temperature Range	-55 to 150	°C
$T_J$	Operating Junction Temperature Range	-55 to 150	°C

## Thermal Data

Symbol	Parameter	Value	Unit
$R_{thj-c}$	Thermal Resistance Junction-case	Max. 2.5	°C/W
$R_{thj-a}$	Thermal Resistance Junction-ambient	Max. 62	°C/W



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## Electrical Characteristics@ $T_j=25^\circ\text{C}$ (unless otherwise specified)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
$\text{BV}_{\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$ , $I_{\text{D}}=250\mu\text{A}$	30	-	-	V
$\Delta \text{BV}_{\text{DSS}}/\Delta T_j$	Breakdown Voltage Temperature Coefficient	Reference to $25^\circ\text{C}$ , $I_{\text{D}}=1\text{mA}$	-	0.037	-	$\text{V}/^\circ\text{C}$
$R_{\text{DS}(\text{ON})}$	Static Drain-Source On-Resistance	$V_{\text{GS}}=10\text{V}$ , $I_{\text{D}}=20\text{A}$	-	14	17	$\text{m}\Omega$
		$V_{\text{GS}}=4.5\text{V}$ , $I_{\text{D}}=16\text{A}$	-	20	23	$\text{m}\Omega$
$V_{\text{GS}(\text{th})}$	Gate Threshold Voltage	$V_{\text{DS}}=V_{\text{GS}}$ , $I_{\text{D}}=250\mu\text{A}$	1	-	3	V
$g_{\text{fs}}$	Forward Transconductance	$V_{\text{DS}}=10\text{V}$ , $I_{\text{D}}=20\text{A}$	-	26	-	S
$I_{\text{DSS}}$	Drain-Source Leakage Current ( $T_j=25^\circ\text{C}$ )	$V_{\text{DS}}=30\text{V}$ , $V_{\text{GS}}=0\text{V}$	-	-	1	$\text{uA}$
	Drain-Source Leakage Current ( $T_j=150^\circ\text{C}$ )	$V_{\text{DS}}=24\text{V}$ , $V_{\text{GS}}=0\text{V}$	-	-	25	$\text{uA}$
$I_{\text{GSS}}$	Gate-Source Leakage	$V_{\text{GS}}= \pm 20\text{V}$	-	-	$\pm 100$	$\text{nA}$
$Q_g$	Total Gate Charge <sup>2</sup>	$I_{\text{D}}=20\text{A}$	-	17	-	nC
$Q_{\text{gs}}$	Gate-Source Charge	$V_{\text{DS}}=24\text{V}$	-	3	-	nC
$Q_{\text{gd}}$	Gate-Drain ("Miller") Charge	$V_{\text{GS}}=5\text{V}$	-	10	-	nC
$t_{\text{d}(\text{on})}$	Turn-on Delay Time <sup>2</sup>	$V_{\text{DS}}=15\text{V}$	-	7.2	-	ns
$t_r$	Rise Time	$I_{\text{D}}=20\text{A}$	-	60	-	ns
$t_{\text{d}(\text{off})}$	Turn-off Delay Time	$R_G=3.3\Omega$ , $V_{\text{GS}}=10\text{V}$	-	22.5	-	ns
$t_f$	Fall Time	$R_D=0.75\Omega$	-	10	-	ns
$C_{\text{iss}}$	Input Capacitance	$V_{\text{GS}}=0\text{V}$	-	800	-	pF
$C_{\text{oss}}$	Output Capacitance	$V_{\text{DS}}=25\text{V}$	-	380	-	pF
$C_{\text{rss}}$	Reverse Transfer Capacitance	f=1.0MHz	-	133	-	pF

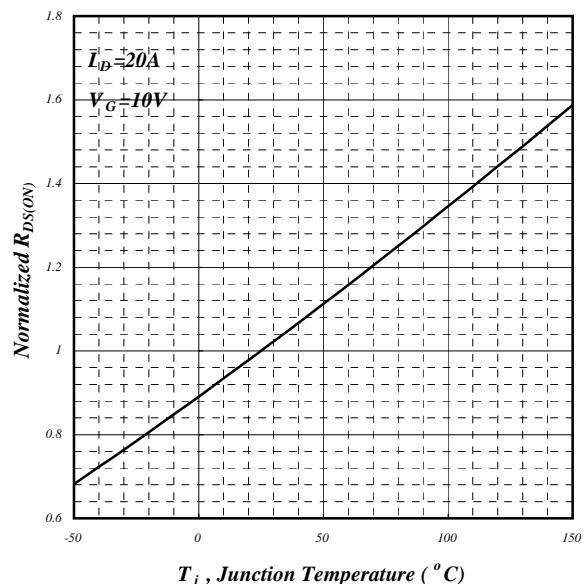
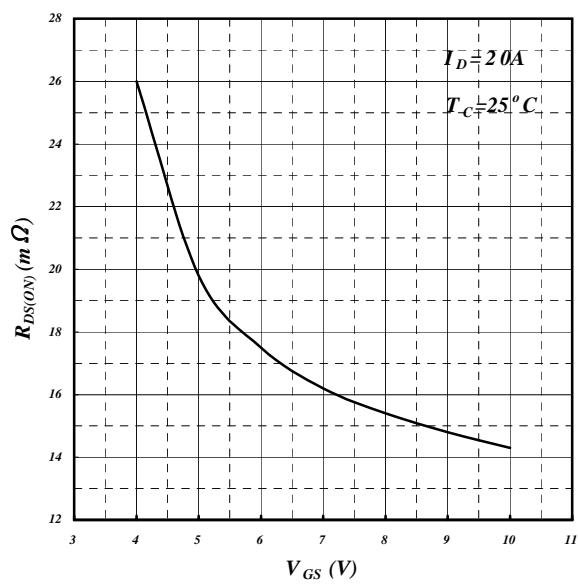
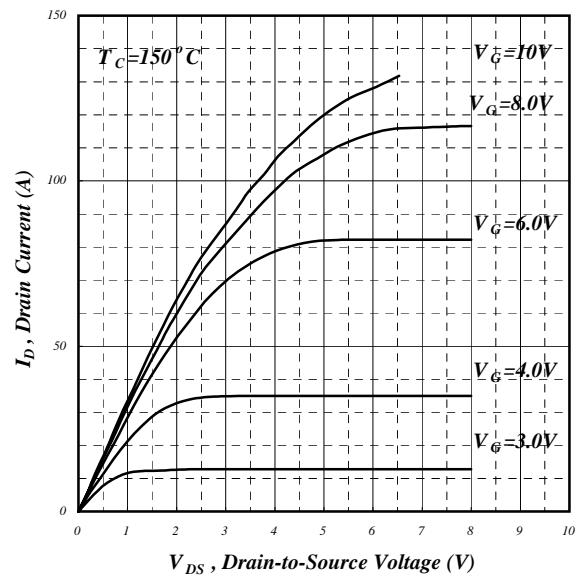
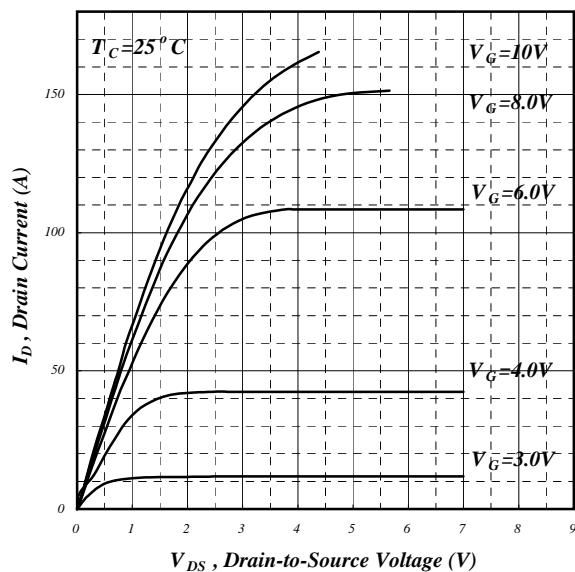
## Source-Drain Diode

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
$I_s$	Continuous Source Current ( Body Diode )	$V_D=V_G=0\text{V}$ , $V_S=1.3\text{V}$	-	-	40	A
$I_{\text{SM}}$	Pulsed Source Current ( Body Diode ) <sup>1</sup>		-	-	169	A
$V_{\text{SD}}$	Forward On Voltage <sup>2</sup>	$T_j=25^\circ\text{C}$ , $I_s=40\text{A}$ , $V_{\text{GS}}=0\text{V}$	-	-	1.3	V

## Notes:

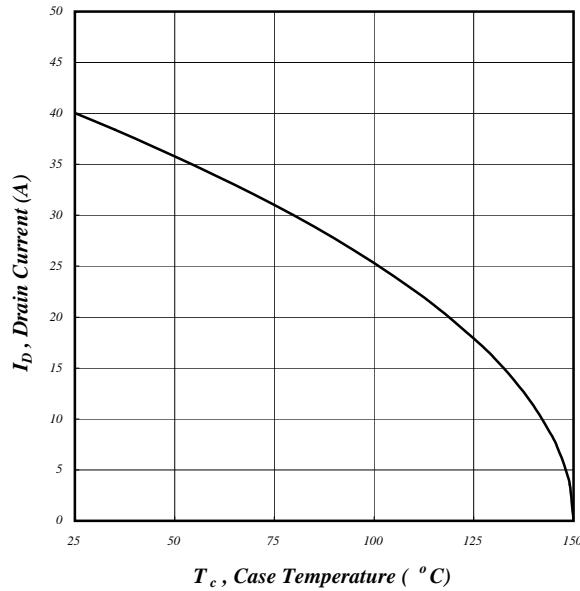
1.Pulse width limited by safe operating area.

2.Pulse width  $\leq 300\text{us}$  , duty cycle  $\leq 2\%$ .

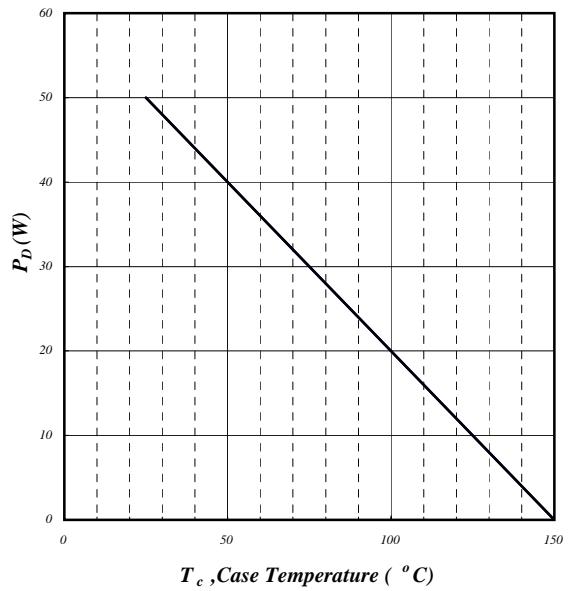




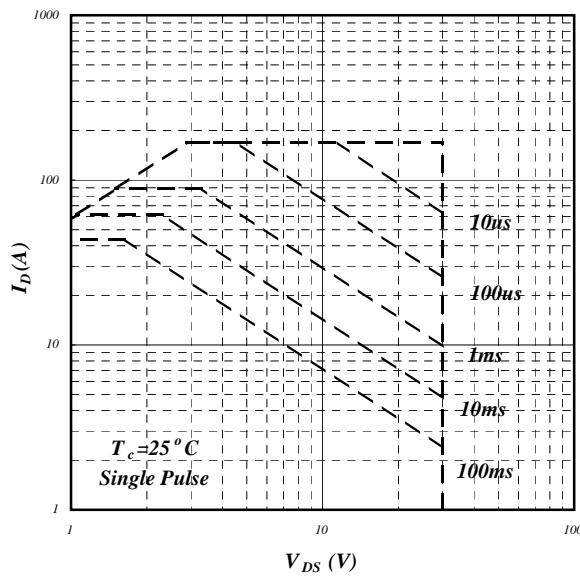
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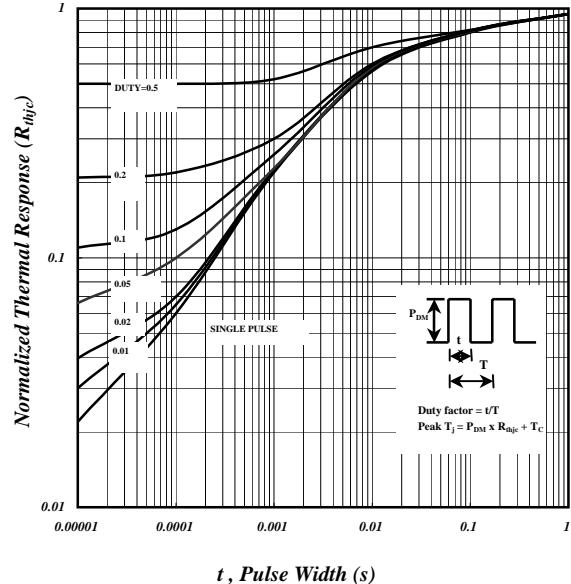
**Fig 5. Maximum Drain Current v.s.  
Case Temperature**



**Fig 6. Typical Power Dissipation**



**Fig 7. Maximum Safe Operating Area**



**Fig 8. Effective Transient Thermal Impedance**

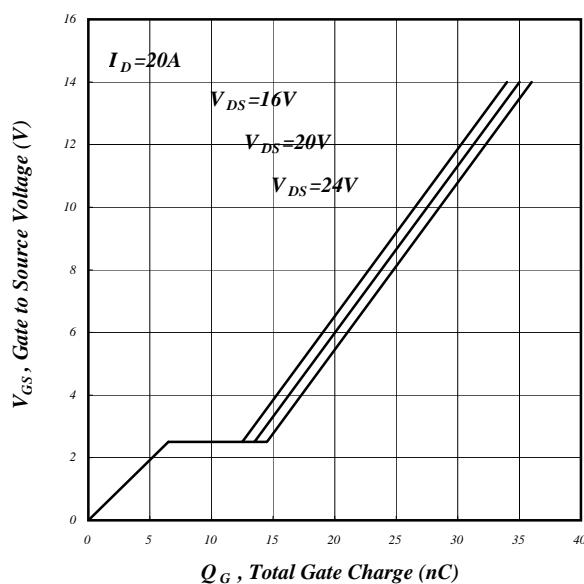


Fig 9. Gate Charge Characteristics

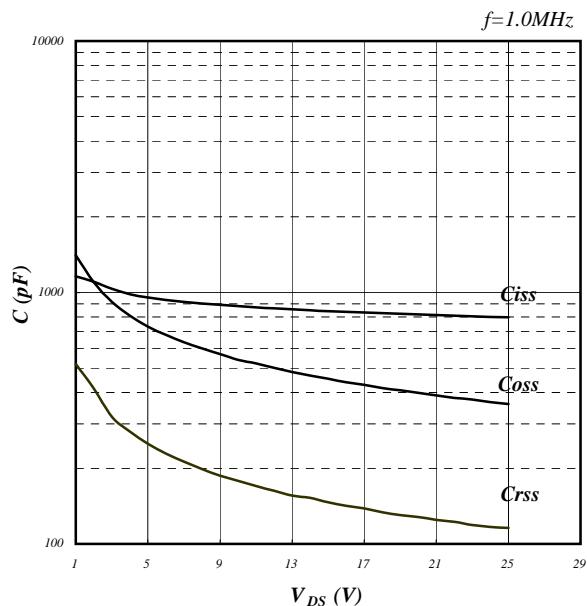


Fig 10. Typical Capacitance Characteristics

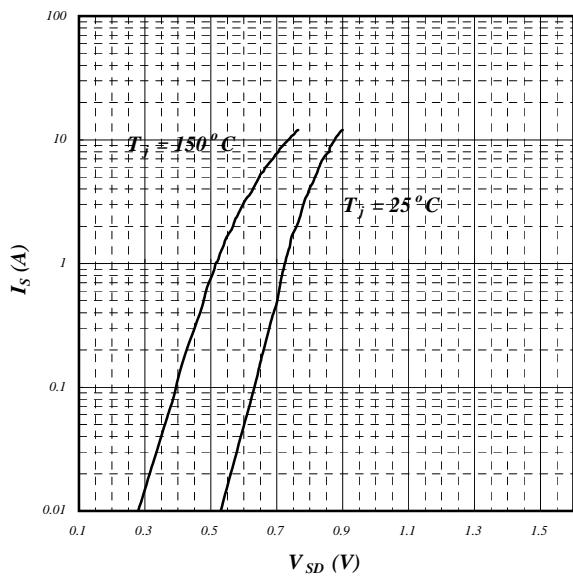


Fig 11. Forward Characteristic of Reverse Diode

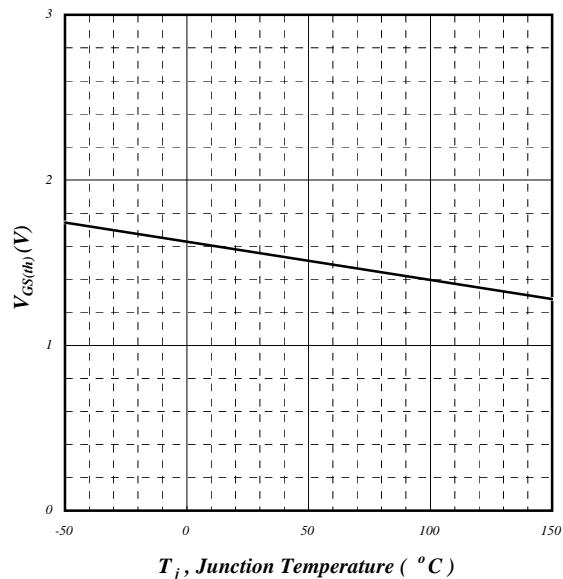
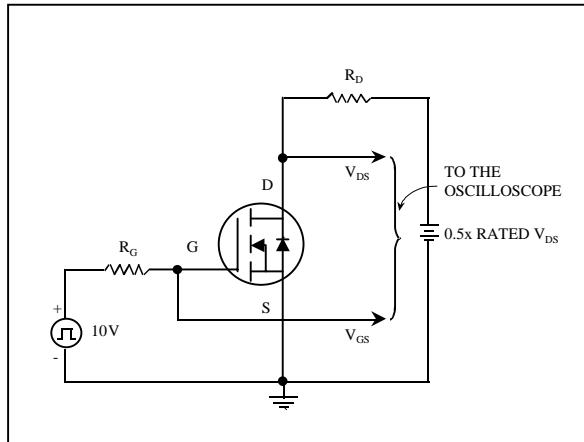


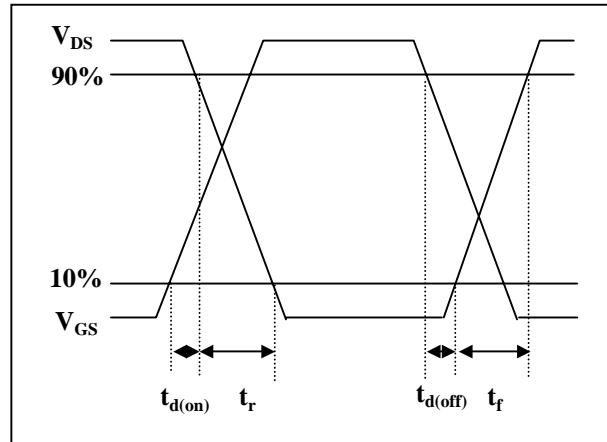
Fig 12. Gate Threshold Voltage v.s. Junction Temperature



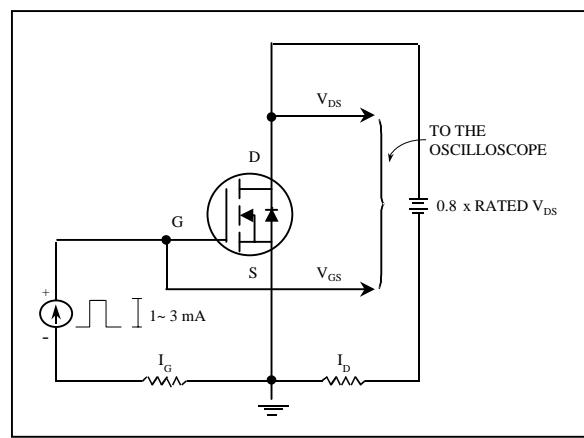
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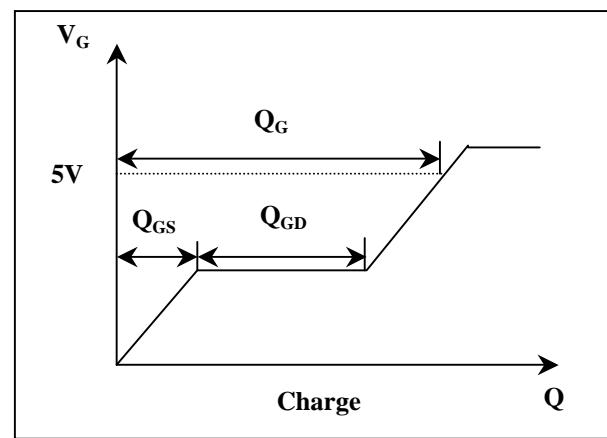
**Fig 13. Switching Time Circuit**



**Fig 14. Switching Time Waveform**



**Fig 15. Gate Charge Circuit**



**Fig 16. Gate Charge Waveform**